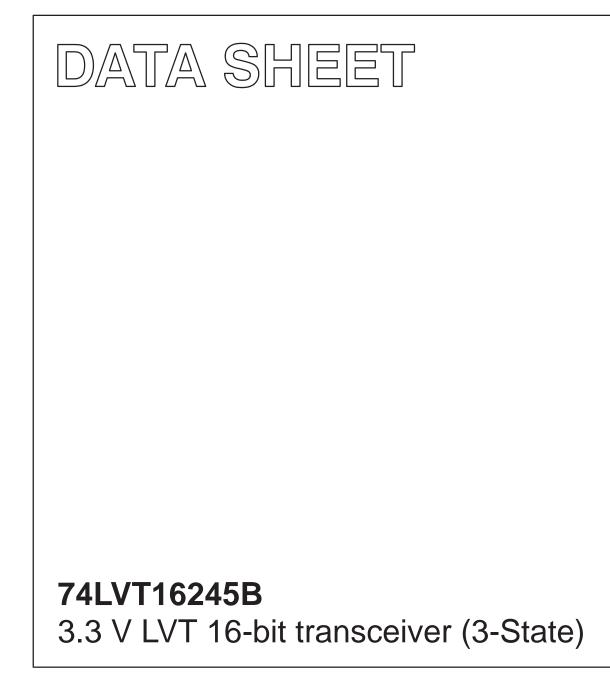
INTEGRATED CIRCUITS



Product data Supersedes data of 1998 Feb 19 2002 Oct 31



74LVT16245B

FEATURES

- 16-bit bidirectional bus interface
- 3-State buffers
- Output capability: +64 mA / -32 mA
- TTL input and output switching levels
- Input and output interface capability to systems at 5 V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power-up 3-State
- No bus current loading when output is tied to 5 V bus
- Latch-up protection exceeds 500 mA per JEDEC Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model

QUICK REFERENCE DATA

DESCRIPTION

The 74LVT16245B is a high-performance BiCMOS product designed for V_{CC} operation at 3.3 V.

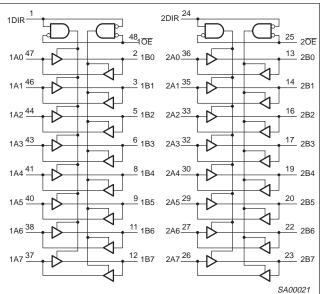
This device is a 16-bit transceiver featuring non-inverting 3-State bus compatible outputs in both send and receive directions. The control function implementation minimizes external timing requirements. The device features an Output Enable (OE) input for easy cascading and a Direction (DIR) input for direction control.

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25 °C	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nBx or nBx to nAx	C _L = 50 pF; V _{CC} = 3.3 V	1.9	ns
C _{IN}	Input capacitance DIR, OE	$V_{I} = 0 V \text{ or } 3.0 V$	3	pF
C _{I/O}	I/O pin capacitance	$V_{I/O} = 0 V \text{ or } 3.0 V$	9	pF
I _{CCZ}	Total supply current	Outputs disabled; $V_{CC} = 3.6 V$	70	μA

ORDERING INFORMATION

TYPE NUMBER	TYPE NUMBER PACKAGE TEMPERATURE RA		DWG NUMBER
74LVT16245BDL	48-Pin Plastic SSOP Type III	–40 °C to +85 °C	SOT370-1
74LVT16245BDGG	48-Pin Plastic TSSOP Type II	–40 °C to +85 °C	SOT362-1
74LVT16245BEV	56VFBGA Ball Grid Array	–40 °C to +85 °C	SOT702-1

LOGIC SYMBOL

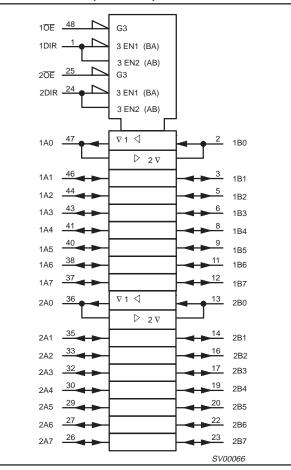


NOTE:

Pin numbers are shown for SSOP and TSSOP packages only.

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LOGIC SYMBOL (IEEE/IEC)



NOTE:

Pin numbers are shown for SSOP and TSSOP packages only.

FUNCTION TABLE

INP	INPUTS		OUTPUTS
nOE	nDIR	nAx	nBx
L	L	nAx = nBx	Inputs
L	Н	Inputs	nBx = nAx
Н	Х	Z	Z

H = High voltage level

L = Low voltage level

X = Don't care

Z = High Impedance "off" state

PIN CONFIGURATION

48-pin SSOP and TSSOP

	$\neg \neg$	
1DIR	1	48 1 0E
1B0 🔤	2	47 1A0
1B1	3	46 1A1
GND -	4	45 GND
1B2	5	44 1A2
1B3	6	43 1A3
V _{CC}	7	42 V _{CC}
1B4	8	41 1A4
1B5	9	40 1A5
GND 1	10	39 GND
1B6 [1	11	38 1A6
1B7 [1	2	37 1A7
2B0 -	13	36 2A0
2B1 [1	4	35 2A1
GND 1	15	34 GND
2B2 [1	16	33 2A2
2B3 [1	17	32 2A3
V _{CC} [1	8	31 V _{CC}
2B4 [1	19	30 2A4
2B5 2	20	29 2A5
GND 2	21	28 GND
2B6 2	22	27 2A6
2B7 2	23	26 2A7
2DIR 2	24	25 2 0E
	SWOO	0061

PIN DESCRIPTION

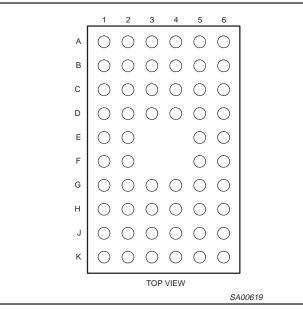
48-pin SSOP and TSSOP

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 24	nDIR	Direction control input
47, 46, 44, 43, 41, 40, 38, 37, 36, 35, 33, 32, 30, 29, 27, 26	nA0 – nA7	Data inputs/outputs (A side)
2, 3, 5, 6, 8, 9, 11, 12, 13, 14, 16, 17, 19, 20, 22, 23	nB0 – nB7	Data inputs/outputs (B side)
25, 48	n <mark>OE</mark>	Output enable input (active-Low)
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V _{CC}	Positive supply voltage

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PIN CONFIGURATION

56-ball VFBGA terminal assignments



PIN DESCRIPTION

56-ball VFBGA terminal assignments

	1	2	3	4	5	6
А	1DIR	NC	NC	NC	NC	1 0E
В	1B1	1B0	GND	GND	1A0	1A1
С	1B3	1B2	V _{CC}	V _{CC}	1A2	1A3
D	1B5	1B4	GND	GND	1A4	1A5
E	1B7	1B6			1A6	1A7
F	2B0	2B1			2A1	2A0
G	2B2	2B3	GND	GND	2A3	2A2
н	2B4	2B5	V _{CC}	V _{CC}	2A5	2A4
J	2B6	2B7	GND	GND	2A7	2A6
к	2DIR	NC	NC	NC	NC	2 0E

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ABSOLUTE MAXIMUM RATINGS^{1,2}

SYMBOL	PARAMETER CONDITIONS		RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +4.6	V
I _{IK}	DC input diode current	V ₁ < 0	-50	mA
VI	DC input voltage ³		-0.5 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	Output in OFF or HIGH state	-0.5 to +7.0	V
		Output in LOW state	128	
IOUT	DC output current	Output in HIGH state	-64	mA
T _{stg}	Storage temperature range		-65 to +150	°C

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction 2.

The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS		UNIT
STWBUL	PARAMETER	MIN	MAX	UNIT
V _{CC}	DC supply voltage	2.7	3.6	V
VI	Input voltage	0	5.5	V
V _{IH}	HIGH-level input voltage	2.0		V
V _{IL}	/IL Input voltage		0.8	V
I _{ОН}	HIGH-level output current		-32	mA
I _{OL}	LOW-level output current		32	mA
	LOW-level output current; current duty cycle \leq 50%; f \geq 1 kHz		64	
$\Delta t/\Delta v$	Input transition rise or fall rate; Outputs enabled		10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

DC ELECTRICAL CHARACTERISTICS

					LIMITS		
SYMBOL	PARAMETER	TEST CONDITIONS		Temp = -	emp = −40 °C to +85 °C		
		T T		MIN	TYP ¹	MAX	
V _{IK}	Input clamp voltage	$V_{CC} = 2.7 \text{ V}; I_{IK} = -18 \text{ mA}$			-0.85	-1.2	V
		$V_{CC} = 2.7$ V to 3.6 V; $I_{OH} = -100 \ \mu A$		V _{CC} -0.2	V _{CC}		
V _{OH}	High-level output voltage	V _{CC} = 2.7 V; I _{OH} = -8 mA		2.4	2.5		V
		V _{CC} = 3.0 V; I _{OH} = -32 mA		2.0	2.3		
		V _{CC} = 2.7 V; I _{OL} = 100 μA			0.07	0.2	
		V _{CC} = 2.7 V; I _{OL} = 24 mA			0.3	0.5	
V _{OL}	Low-level output voltage	V _{CC} = 3.0 V; I _{OL} = 16 mA			0.25	0.4	V
		V _{CC} = 3.0 V; I _{OL} = 32 mA			0.3	0.5	
		V _{CC} = 3.0 V; I _{OL} = 64 mA			0.4	0.55	
		$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = V_{CC} \text{ or GND}$			0.1	±1	
		V _{CC} = 0 V or 3.6 V; V _I = 5.5 V	Control pins		0.1	10	
I _I	Input leakage current	V _{CC} = 3.6 V; V _I = 5.5 V			0.1	20	μA
		$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = V_{CC}$	I/O Data pins ⁴		0.5	10	
		$V_{CC} = 3.6 \text{ V}; \text{ V}_{I} = 0$			0.1	-5	
I _{OFF}	Output off current	$V_{CC} = 0 \text{ V}; \text{ V}_{I} \text{ or } \text{ V}_{O} = 0 \text{ V to } 4.5 \text{ V}$			0.1	±100	μΑ
		V _{CC} = 3 V; V _I = 0.8 V		75	135		
I _{HOLD}	Bus Hold current A or B outputs ⁶	$V_{CC} = 3 \text{ V}; \text{ V}_{I} = 2.0 \text{ V}$		-75	-135		μΑ
		$V_{CC} = 0 V \text{ to } 3.6 V; V_{CC} = 3.6 V$		±500			
I_{EX}	Current into an output in the High state when $V_O > V_{CC}$	$V_{O} = 5.5 \text{ V}; V_{CC} = 3.0 \text{ V}$			75	125	μΑ
I _{PU/PD}	Power up/down 3-State output current ³	$V_{CC} \le 1.2 \text{ V}; V_O = 0.5 \text{ V} \text{ to } V_{CC}; V_I = \text{GND or } V_{CC}; OE/OE = \text{Don't care}$			40	±100	μΑ
I _{CCH}		V_{CC} = 3.6 V; Outputs HIGH, V_{I} = GND or V_{CC} , I_{O} = 0			0.07	0.12	
I _{CCL}	Quiescent supply current	$V_{CC} = 3.6 \text{ V}$; Outputs LOW, $V_{I} = \text{GND or } V_{CC}$, $I_{O} = 0$			4.7	6	mA
I _{CCZ}	1	V_{CC} = 3.6 V; Outputs Disabled; V _I = GN	O or V_{CC} , $I_{O} = 0^5$		0.07	0.12	
ΔI_{CC}	Additional supply current per input pin ²	$V_{CC} = 3 V$ to 3.6 V; One input at V_{CC} =0. Other inputs at V_{CC} or GND	6 V,		0.1	0.2	mA

NOTES: 1. All typical values are at $V_{CC} = 3.3$ V and $T_{amb} = 25$ °C. 2. This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND 3. This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 msec. From $V_{CC} = 1.2$ V to $V_{CC} = 3.3$ V ± 0.3 V a transition time of 100 µsec is permitted. This parameter is valid for $T_{amb} = 25$ °C only. 4. Unused pins at V_{CC} or GND. 5. I_{CCZ} is measured with outputs pulled to V_{CC} or GND. 6. This is the hus-hold overdrive current required to force the input to the opposite logic state.

6. This is the bus-hold overdrive current required to force the input to the opposite logic state.

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AC CHARACTERISTICS

GND = 0 V; $t_R = t_F = 2.5$ ns; $C_L = 50$ pF; $R_L = 500 \Omega$; $T_{amb} = -40 \ ^\circ C$ to +85 $^\circ C$.

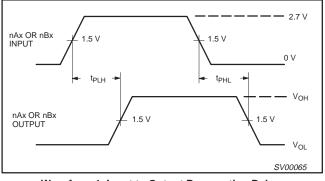
				LI	MITS		
SYMBOL	PARAMETER	WAVEFORM	Vcc	= 3.3 V +0	.3 V	V _{CC} = 2.7 V	UNIT
			MIN	TYP ¹	MAX	MAX	
t _{PLH} t _{PHL}	Propagation delay nAx to nBx or nBx to nAx	1	1.0 1.0	1.9 1.7	3.3 3.3	3.5 3.5	ns
t _{PZH} t _{PZL}	Output enable time to HIGH and LOW level	2	1.0 1.0	2.8 2.8	4.5 4.1	5.3 5.1	ns
t _{PHZ} t _{PLZ}	Output disable time from HIGH and LOW Level	2	1.5 1.5	3.2 3.0	5.1 4.6	5.7 4.6	ns

NOTE:

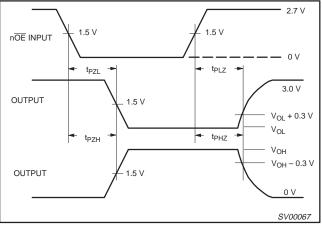
1. All typical values are at V_{CC} = 3.3 V and T_{amb} = 25 °C.

AC WAVEFORMS

 V_{M} = 1.5 V; V_{IN} = GND to 2.7 V.



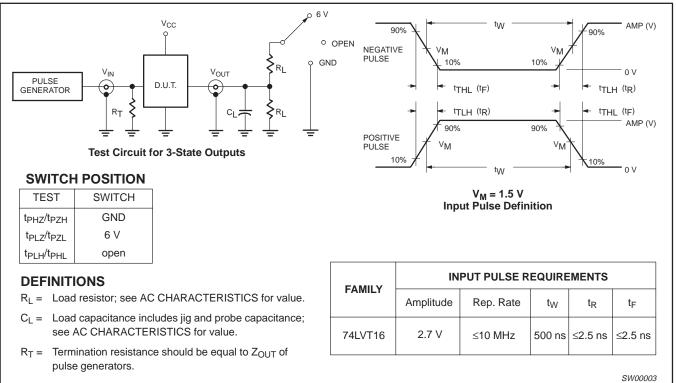
Waveform 1. Input to Output Propagation Delays

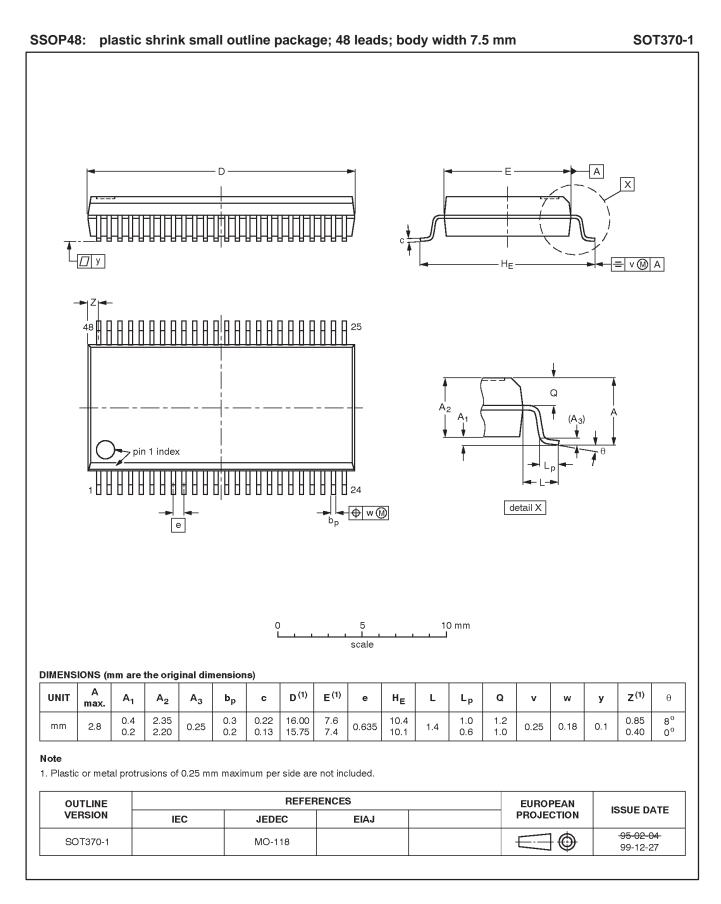


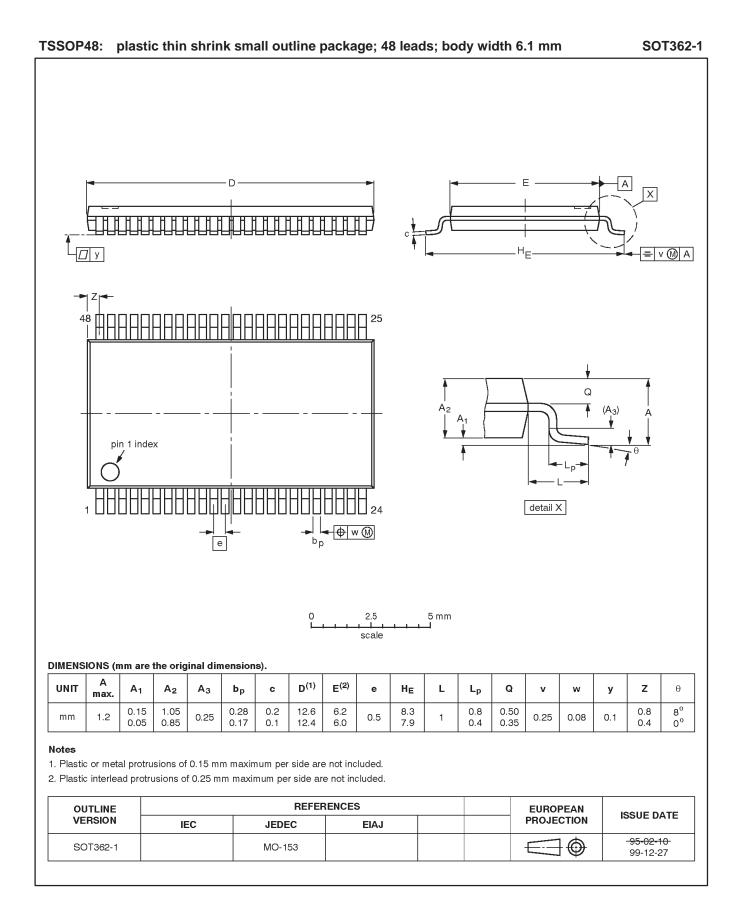
Waveform 2. 3-State Output Enable and Disable Times

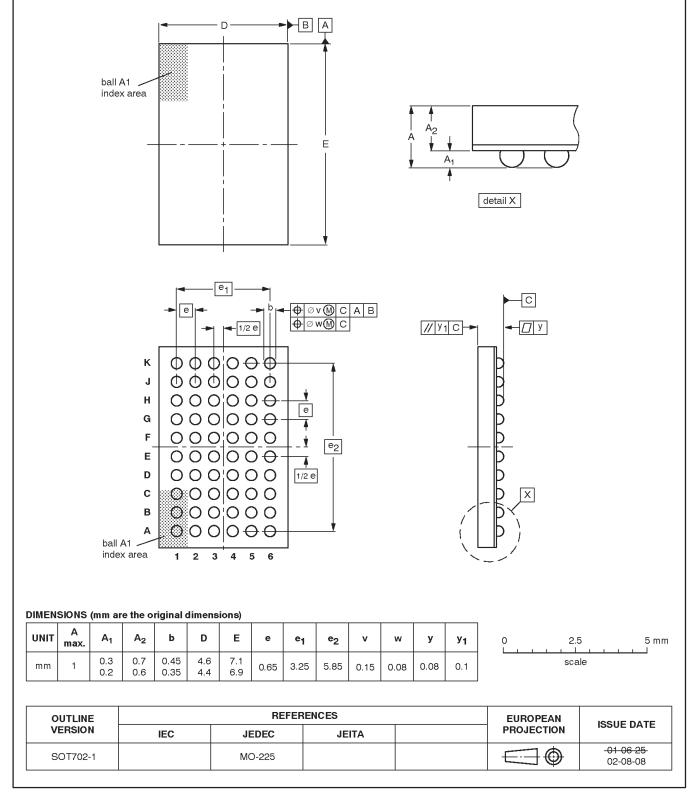
74LVT16245B

TEST CIRCUIT AND WAVEFORMS









VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body 4.5 x 7 x 0.65 mm

SOT702-1

REVISION HISTORY

Rev	Date	Description
_3	20021031	Product data (9397 750 09135); supersedes 74LVT16245B_2 of 1998 Feb 19 (9397 750 03552).
		Engineering Change Notice 853–1753 27400 (date: 20011203).
		Modifications:
		 Add VFBGA56 (EV) package option.

Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2] [3]}	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

Definitions

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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